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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







Darlington Transistors

NPN Silicon

Features

• These are Pb-Free Devices*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V _{CES}	30	Vdc
Collector - Base Voltage	V _{CB}	40	Vdc
Emitter -Base Voltage	V _{EB}	10	Vdc
Collector Current - Continuous	Ic	1.0	Adc
Total Power Dissipation @ T _A = 25°C Derate above T _A = 25°C	P _D	625 12	mW mW/°C
Total Power Dissipation @ T _C = 25°C Derate above T _C = 25°C	P _D	1.5 12	W mW/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-55 to +150	°C

THERMAL CHARACTERISTICS

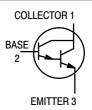
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	83.3	°C/W

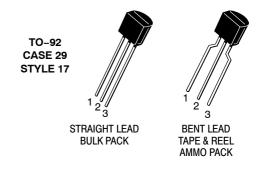
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



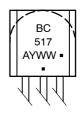
ON Semiconductor®

http://onsemi.com





MARKING DIAGRAM



= Assembly Location

= Year WW = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
BC517G	TO-92 (Pb-Free)	5000 Units / Bulk
BC517RL1G	TO-92 (Pb-Free)	2000 / Tape & Reel
BC517ZL1G	TO-92 (Pb-Free)	2000 / Ammo Pack

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS	OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (I _C = 2.0 mAdc, I _{BE} = 0)	V _{(BR)CES}	30	-	-	Vdc	
Collector – Base Breakdown Voltage ($I_C = 10 \mu Adc, I_E = 0$)	V _{(BR)CBO}	40	-	-	Vdc	
Emitter – Base Breakdown Voltage ($I_E = 100 \mu Adc$, $I_C = 0$)	V _{(BR)EBO}	10	-	-	Vdc	
Collector Cutoff Current (V _{CE} = 30 Vdc)	I _{CES}	_	-	500	nAdc	
Collector Cutoff Current (V _{CB} = 30 Vdc, I _E = 0)	I _{CBO}	_	_	100	nAdc	
Emitter Cutoff Current (V _{CB} = 10 Vdc, I _C = 0)	I _{EBO}	_	_	100	nAdc	
ON CHARACTERISTICS (Note 1)	•	•				
DC Current Gain (I _C = 20 mAdc, V _{CE} = 2.0 Vdc)	h _{FE}	30,000	-	-	-	
Collector – Emitter Saturation Voltage (I _C = 100 mAdc, I _B = 0.1 mAdc)	V _{CE(sat)}	_	-	1.0	Vdc	
Collector – Emitter Saturation Voltage (I _C = 10 mAdc, V _{CE} = 5.0 Vdc)	V _{BE(on)}	_	-	1.4	Vdc	
SMALL-SIGNAL CHARACTERISTICS						
Current-Gain – Bandwidth Product (Note 2) (I _C = 10 mAdc, V _{CE} = 5.0 Vdc, f = 100 MHz)	f _T	_	200	_	MHz	

Pulse Test: Pulse Width = 300 μs, Duty Cycle 2.0%.
 f_T = |h_{fe}| • f_{test}

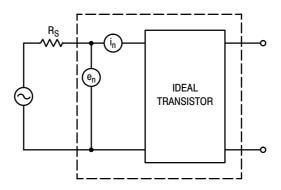


Figure 1. Transistor Noise Model

NOISE CHARACTERISTICS

 $(V_{CE} = 5.0 \text{ Vdc}, T_A = 25^{\circ}C)$

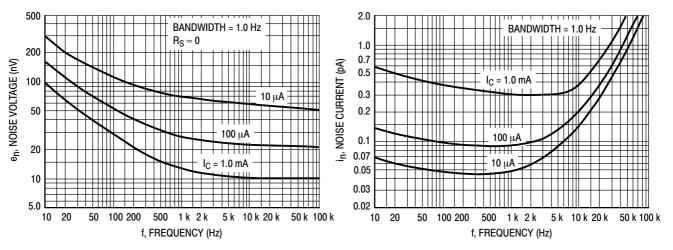


Figure 2. Noise Voltage

Figure 3. Noise Current

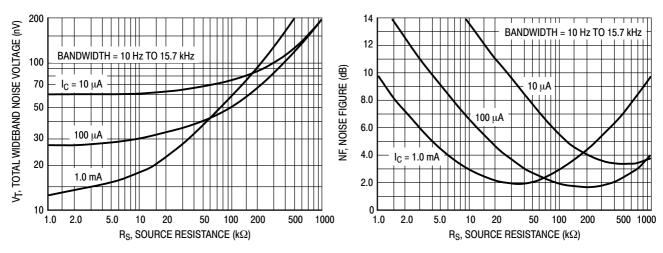
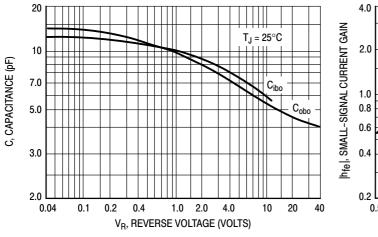


Figure 4. Total Wideband Noise Voltage

Figure 5. Wideband Noise Figure

SMALL-SIGNAL CHARACTERISTICS



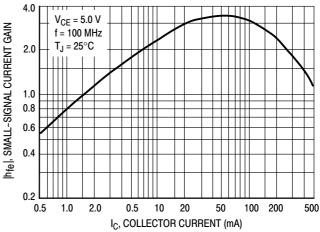
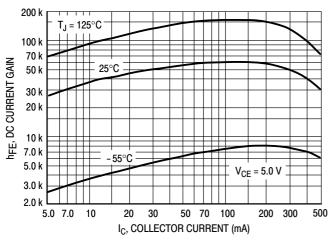


Figure 6. Capacitance

Figure 7. High Frequency Current Gain



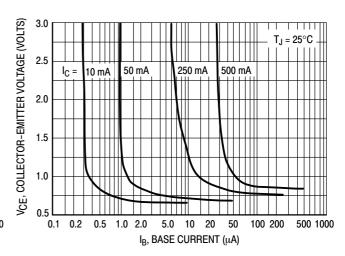
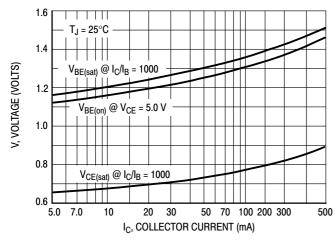


Figure 8. DC Current Gain

Figure 9. Collector Saturation Region



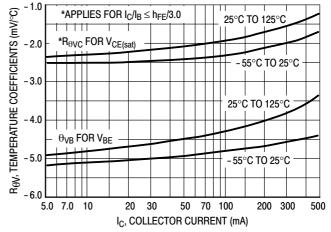


Figure 10. "On" Voltages

Figure 11. Temperature Coefficients

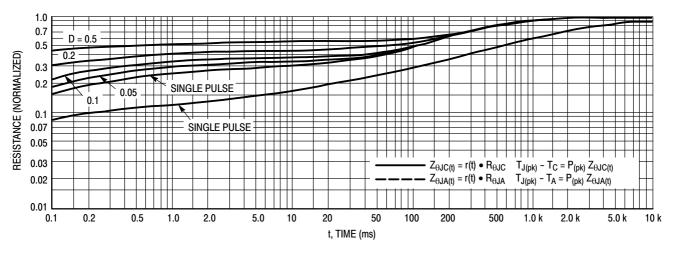


Figure 12. Thermal Response

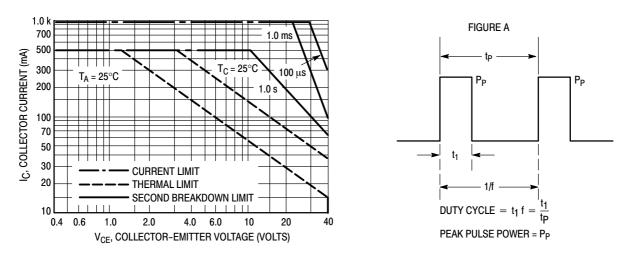
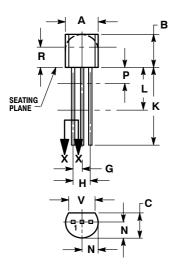


Figure 13. Active Region Safe Operating Area Design Note: Use of Transient Thermal Resistance Data

PACKAGE DIMENSIONS

TO-92 (TO-226) CASE 29-11 **ISSUE AM**



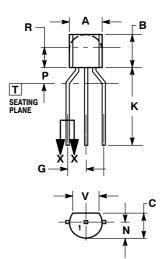
STRAIGHT LEAD **BULK PACK**



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED
- LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500		12.70	
L	0.250		6.35	
N	0.080	0.105	2.04	2.66
Р		0.100		2.54
R	0.115		2.93	
V	0 135		3 43	



BENT LEAD TAPE & REEL AMMO PACK



NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
 CONTOUR OF PACKAGE BEYOND
- DIMENSION R IS UNCONTROLLED
- LEAD DIMENSION IS UNCONTROLLED IN PAND BEYOND DIMENSION K MINIMUM.

	MILLIMETERS		
DIM	MIN MAX		
Α	4.45	5.20	
В	4.32	5.33	
C	3.18	4.19	
D	0.40	0.54	
G	2.40	2.80	
J	0.39	0.50	
K	12.70		
N	2.04	2.66	
P	1.50	4.00	
R	2.93		
٧	3.43		

STYLE 17:

COLLECTOR PIN 1.

BASE

EMITTER

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